



ASE GROUP



日月光半導體 2017第一季法人說明會

2017年4月28日

Safe Harbor Notice



This presentation contains "forward-looking statements" within the meaning of Section 27A of the United States Securities Act of 1933, as amended, and Section 21E of the United States Securities Exchange Act of 1934, as amended. Although these forward-looking statements, which may include statements regarding our future results of operations, financial condition or business prospects, are based on our own information and information from other sources we believe to be reliable, you should not place undue reliance on these forward-looking statements, which apply only as of the date of this press release. The words "anticipate," "believe," "estimate," "expect," "intend," "plan" and similar expressions, as they relate to us, are intended to identify these forward-looking statements in this press release. Our actual results of operations, financial condition or business prospects may differ materially from those expressed or implied in these forward-looking statements for a variety of reasons, including risks associated with cyclicity and market conditions in the semiconductor or electronic industry; changes in our regulatory environment, including our ability to comply with new or stricter environmental regulations and to resolve environmental liabilities; demand for the outsourced semiconductor packaging, testing and electronic manufacturing services we offer and for such outsourced services generally; the highly competitive semiconductor or manufacturing industry we are involved in; our ability to introduce new technologies in order to remain competitive; international business activities; our business strategy; our future expansion plans and capital expenditures; the uncertainties as to whether we can complete the share exchange contemplated by a joint share exchange agreement between Siliconware Precision Industries Co., Ltd. and us; the strained relationship between the Republic of China and the People's Republic of China; general economic and political conditions; the recent global economic crisis; possible disruptions in commercial activities caused by natural or human-induced disasters; fluctuations in foreign currency exchange rates; and other factors. For a discussion of these risks and other factors, please see the documents we file from time to time with the Securities and Exchange Commission, including our 2016 Annual Report on Form 20-F filed on April 21, 2017.



日月光及矽品共同轉換股份協議最新消息

- 台灣公平交易委員會已核准通過日月光與矽品結合案。
- 日月光與矽品於2016年8月25日向中國商務部遞交文件，商務部於2016年12月14日正式立案審查。日月光已於2017年4月12日收到商務部通知本案進入第三階段延長審查。
- 日月光與矽品各已依美國聯邦貿易委員會的要求回覆相關文件，並將持續與聯邦貿易委員會配合以盡速完成調查。



合併綜合損益表

與上一季比較

(未經會計師查核)



(新台幣百萬元)	Q1 / 2017	%	Q4 / 2016	%	季變化
營業收入淨額:					
封裝	29,809	44.8%	33,620	43.6%	-11%
測試	6,365	9.6%	7,303	9.5%	-13%
材料直接銷售	892	1.3%	806	1.0%	11%
電子代工服務	29,355	44.1%	34,627	44.9%	-15%
其它	133	0.2%	772	1.0%	-83%
營業收入淨額合計	66,551	100.0%	77,128	100.0%	-14%
營業毛利	11,978	18.0%	15,377	19.9%	-22%
營業淨利 (淨損)	5,228	7.9%	8,133	10.5%	-36%
稅前淨利 (淨損)	3,857	5.8%	9,669	12.5%	-60%
所得稅利益 (費用)	(886)	-1.3%	(1,274)	-1.7%	
非控制權益	(402)	-0.6%	(430)	-0.6%	
歸屬於本公司業主之淨利	2,569	3.9%	7,965	10.3%	-68%
基本每股盈餘 (新台幣元)	0.33		1.04		-68%
稀釋每股盈餘 (新台幣元)	0.30		0.88		-66%
EBITDA	11,764	17.7%	17,227	22.3%	-32%



合併綜合損益表

與去年同期比較

(未經會計師查核)



(新台幣百萬元)	Q1 / 2017	%	Q1 / 2016	%	年變化
營業收入淨額:					
封裝	29,809	44.8%	28,036	45.0%	6%
測試	6,365	9.6%	5,995	9.6%	6%
材料直接銷售	892	1.3%	892	1.4%	0%
電子代工服務	29,355	44.1%	24,749	39.7%	19%
其它	133	0.2%	2,699	4.3%	-95%
營業收入淨額合計	66,551	100.0%	62,371	100.0%	7%
營業毛利	11,978	18.0%	11,449	18.4%	5%
營業淨利 (淨損)	5,228	7.9%	5,206	8.3%	0%
稅前淨利 (淨損)	3,857	5.8%	5,374	8.6%	-28%
所得稅利益 (費用)	(886)	-1.3%	(1,318)	-2.1%	
非控制權益	(402)	-0.6%	(174)	-0.3%	
歸屬於本公司業主之淨利	2,569	3.9%	3,882	6.2%	-34%
基本每股盈餘 (新台幣元)	0.33		0.51		-35%
稀釋每股盈餘 (新台幣元)	0.30		0.40		-25%
EBITDA	11,764	17.7%	13,229	21.2%	-11%



綜合損益表 – 半導體封裝測試

與上一季比較

(未經會計師查核)



(新台幣百萬元)	Q1 / 2017	%	Q4 / 2016	%	季變化
營業收入淨額:					
封裝	31,061	80.9%	35,242	81.1%	-12%
測試	6,365	16.6%	7,303	16.8%	-13%
材料直接銷售	935	2.4%	898	2.1%	4%
其它	24	0.1%	20	0.0%	20%
營業收入淨額合計	38,385	100.0%	43,463	100.0%	-12%
營業毛利	8,835	23.0%	11,647	26.8%	-24%
營業淨利 (淨損)	3,985	10.4%	6,375	14.7%	-37%
稅前淨利 (淨損)	3,218	8.4%	9,046	20.8%	-64%
所得稅利益 (費用)	(570)	-1.5%	(967)	-2.2%	
非控制權益	(79)	-0.2%	(114)	-0.3%	
歸屬於本公司業主之淨利	2,569	6.7%	7,965	18.3%	-68%
EBITDA	9,800	25.5%	14,746	33.9%	-34%



綜合損益表 – 半導體封裝測試

與去年同期比較

(未經會計師查核)



(新台幣百萬元)	Q1 / 2017	%	Q1 / 2016	%	年變化
營業收入淨額:					
封裝	31,061	80.9%	28,597	80.5%	9%
測試	6,365	16.6%	5,995	16.9%	6%
材料直接銷售	935	2.4%	931	2.6%	0%
其它	24	0.1%	20	0.1%	20%
營業收入淨額合計	38,385	100.0%	35,543	100.0%	8%
營業毛利	8,835	23.0%	7,832	22.0%	13%
營業淨利 (淨損)	3,985	10.4%	3,222	9.1%	24%
稅前淨利 (淨損)	3,218	8.4%	4,464	12.6%	-28%
所得稅利益 (費用)	(570)	-1.5%	(529)	-1.5%	
非控制權益	(79)	-0.2%	(53)	-0.1%	
歸屬於本公司業主之淨利	2,569	6.7%	3,882	10.9%	-34%
EBITDA	9,800	25.5%	10,580	29.8%	-7%

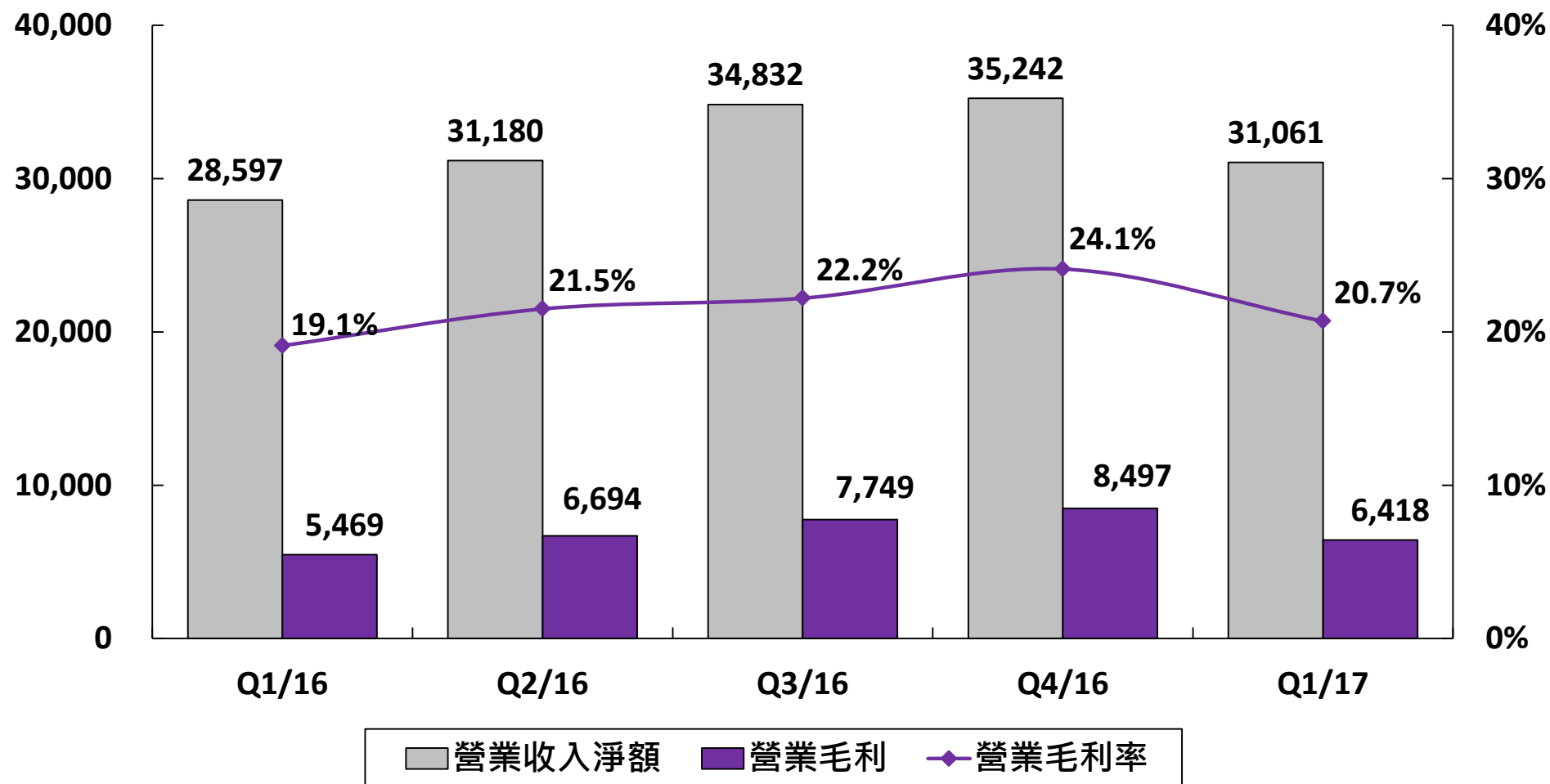


封裝業務

(未經會計師查核)



新台幣百萬元

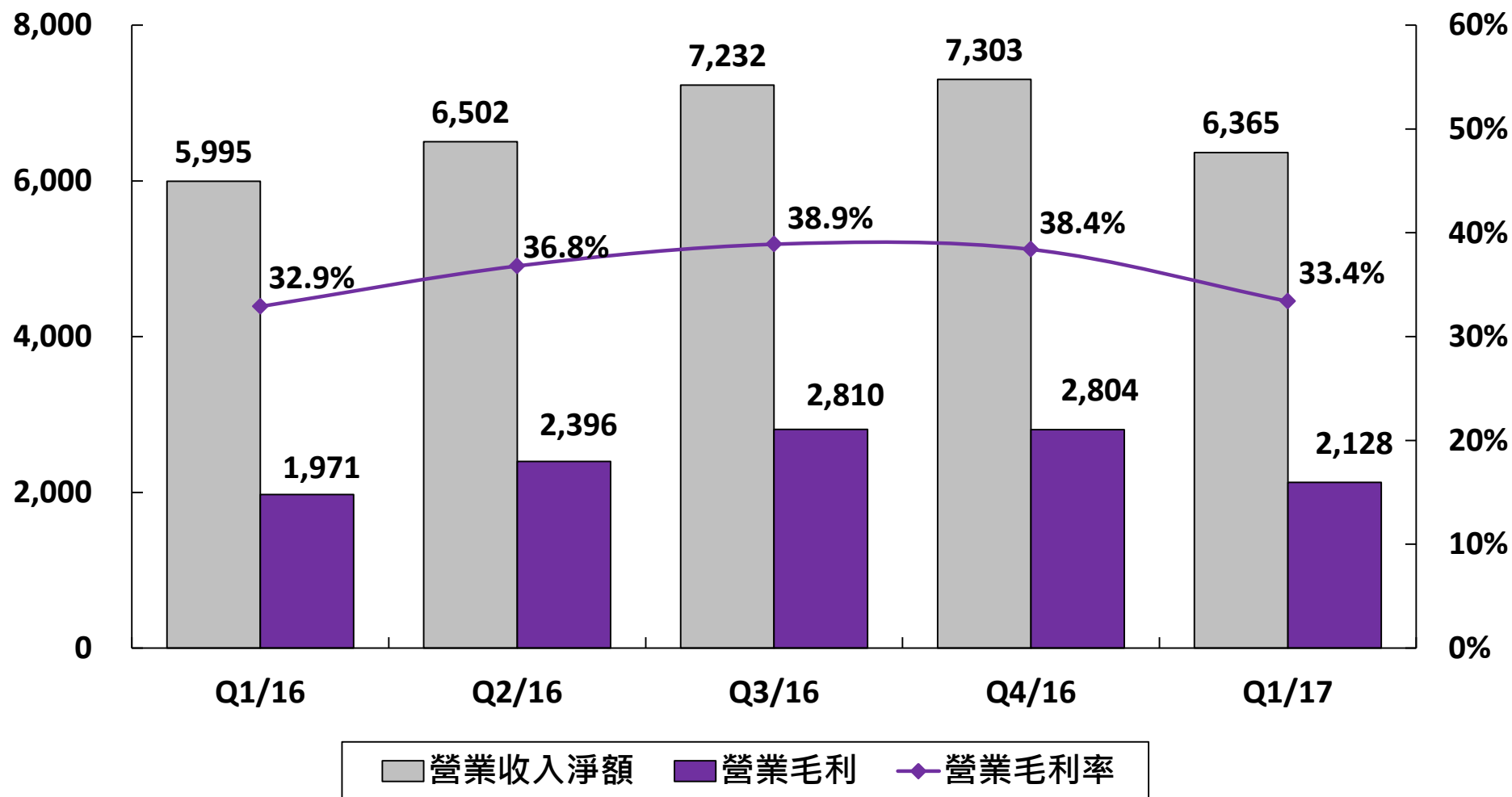


測試業務

(未經會計師查核)



新台幣百萬元

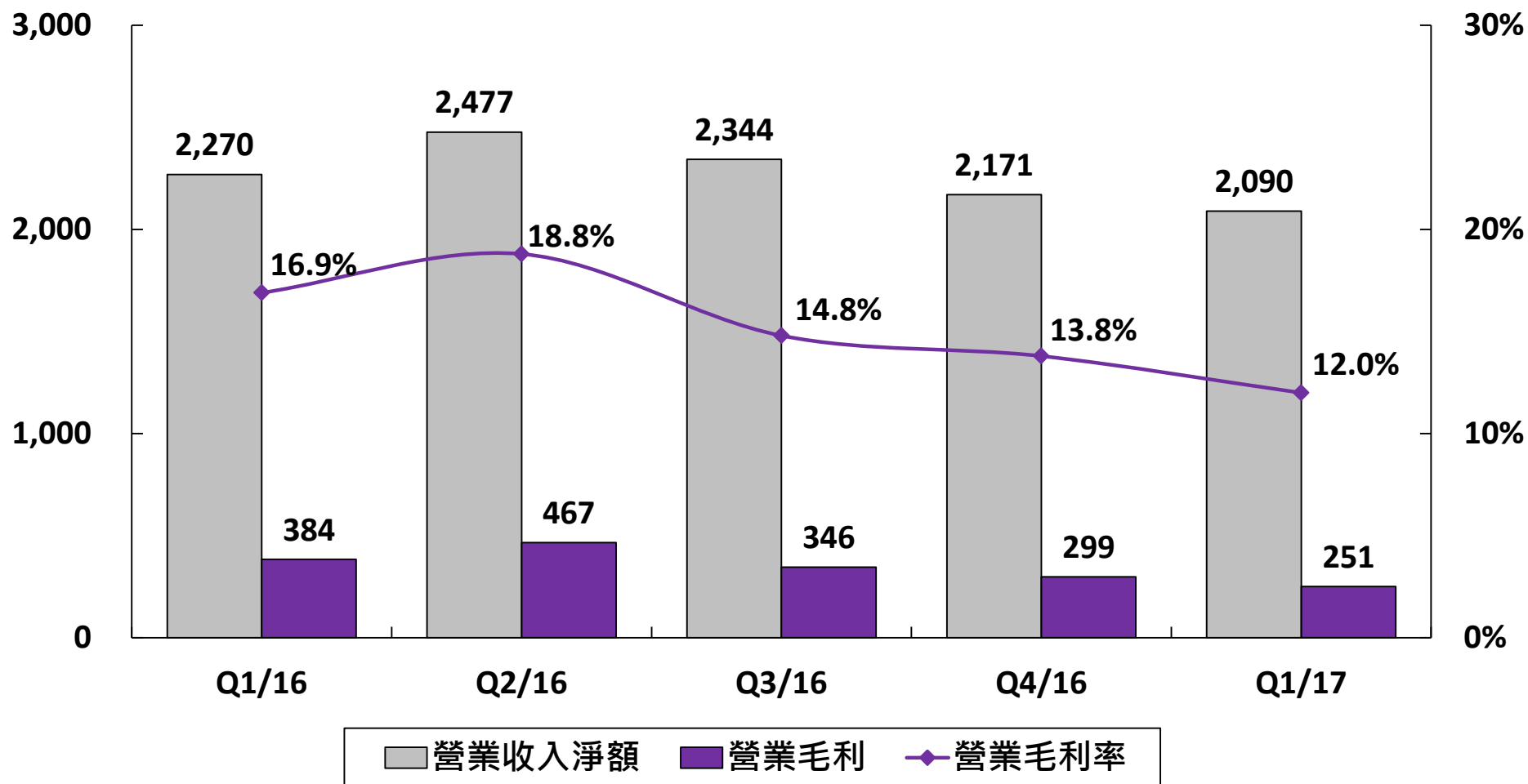


材料業務

(未經會計師查核)



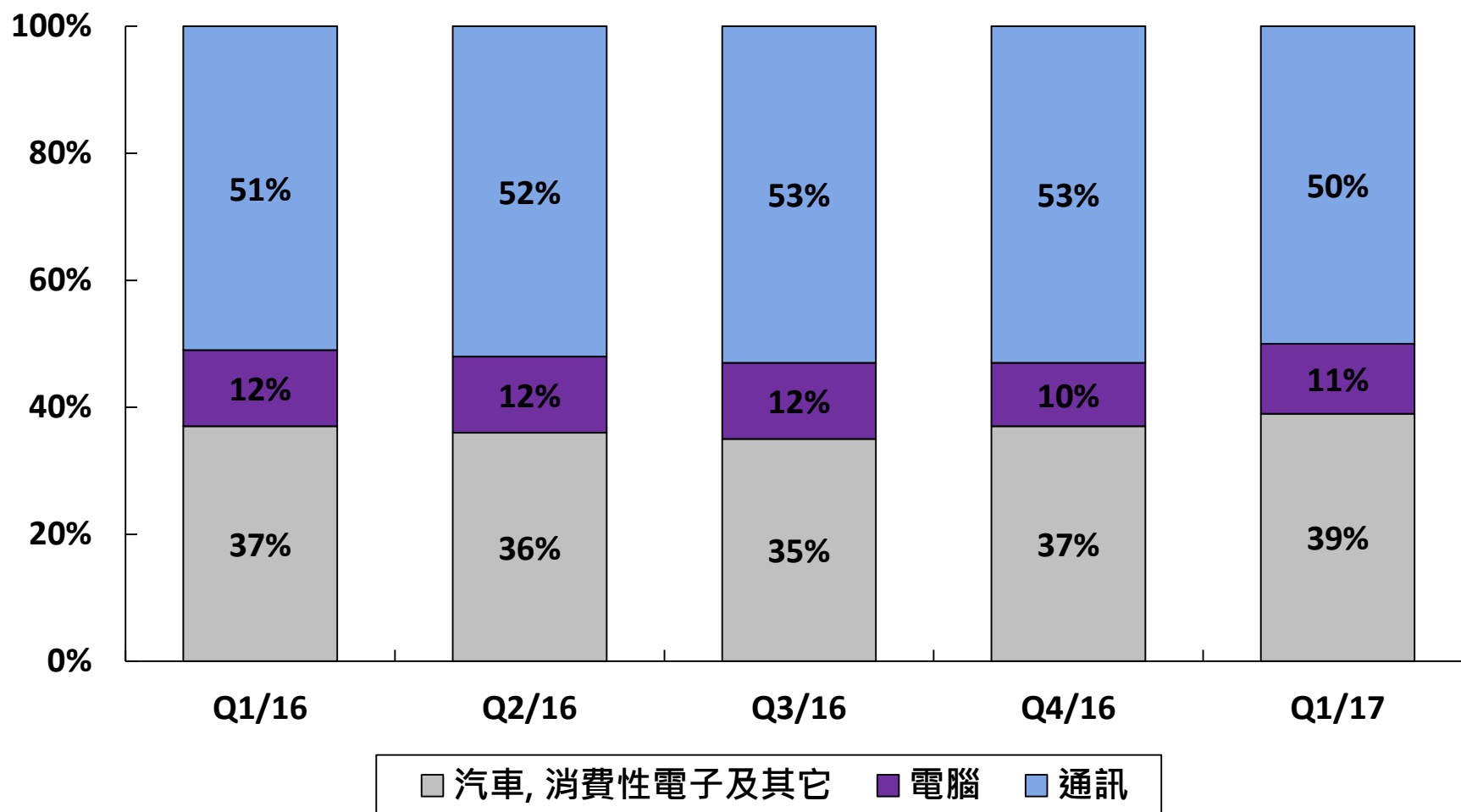
新台幣百萬元



半導體封測營收

產品應用別佔比

(未經會計師查核)

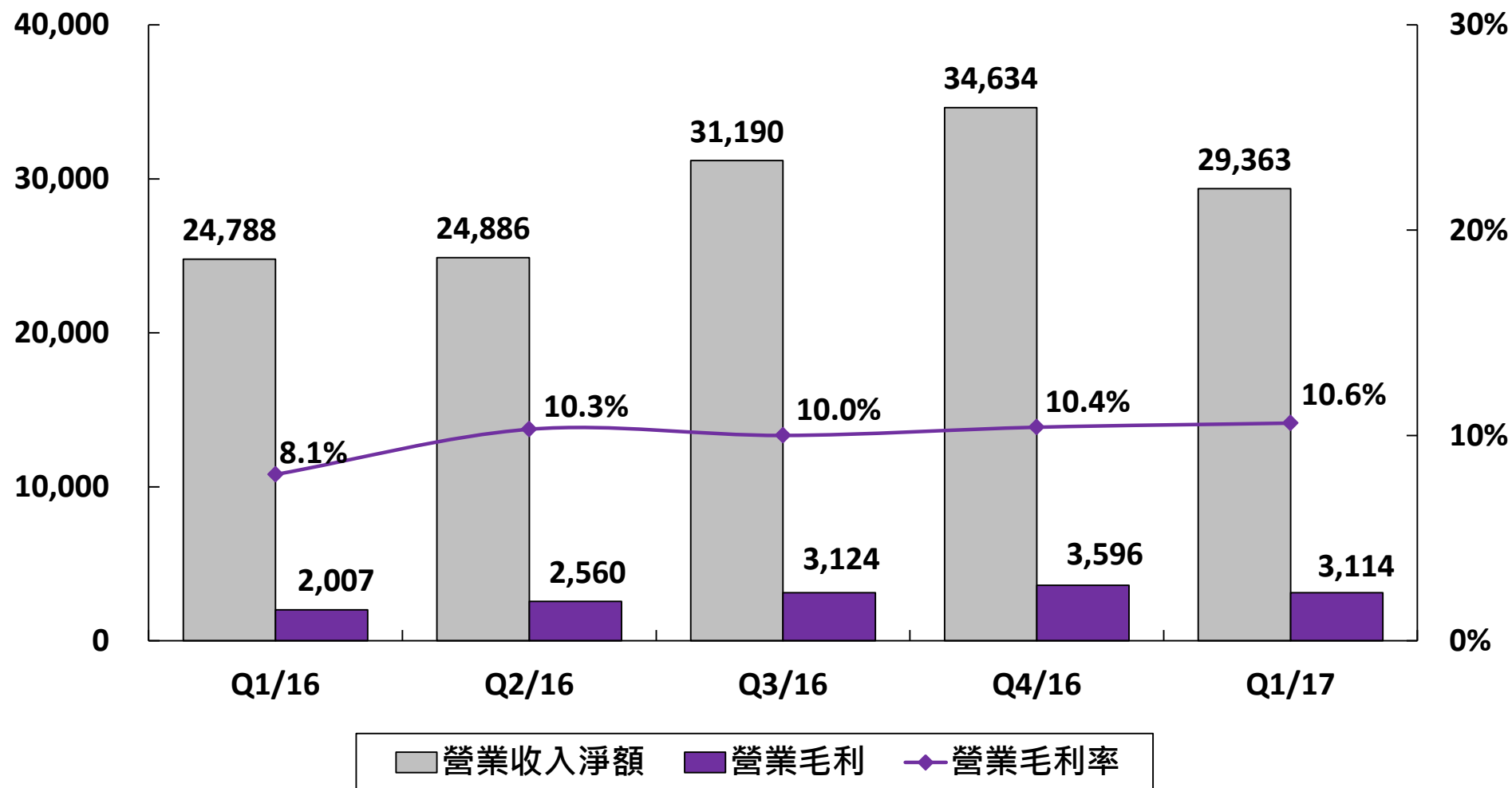


電子代工服務業務

(未經會計師查核)



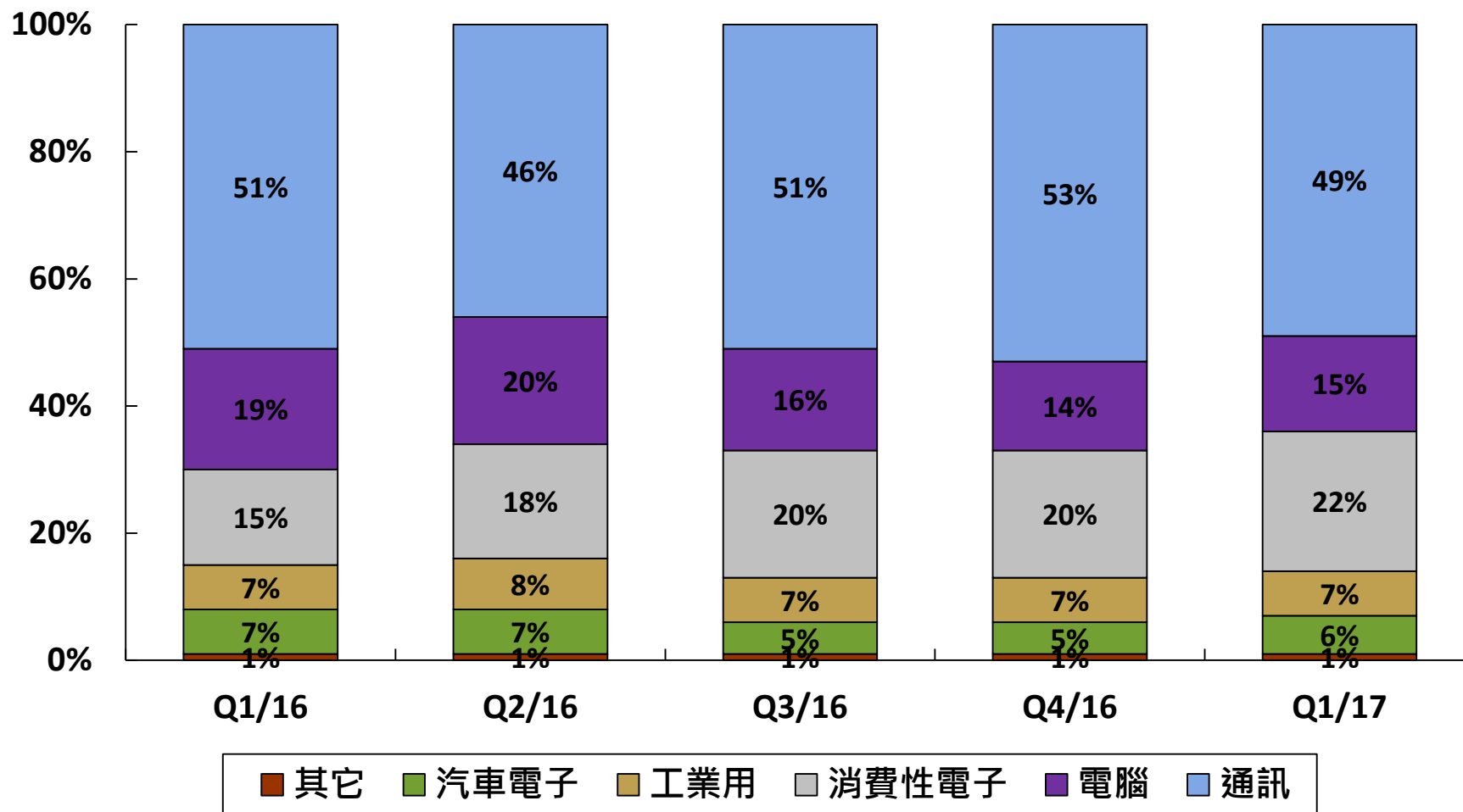
新台幣百萬元



電子代工服務業務

產品應用別

(未經會計師查核)



重要資產負債表項目及財務指標

(未經會計師查核)



(新台幣百萬元)	2017年3月31日	2016年12月31日	季變化
現金及約當現金	42,474	38,392	10.6%
金融資產 - 流動	3,720	3,895	-4.5%
金融資產 - 非流動及採用權益法之投資	52,200	52,174	0.0%
不動產、廠房及設備	140,072	143,880	-2.6%
資產總計	347,549	357,943	-2.9%
短期借款及應付短期票券	13,400	20,956	-36.1%
一年內到期之應付公司債	15,179	9,658	57.2%
一年內到期之長期借款及應付租賃款	7,218	6,683	8.0%
應付公司債	28,476	27,342	4.1%
長期借款及應付租賃款	33,639	47,013	-28.4%
權益總計 (含非控制權益)	176,790	169,347	4.4%
當季 EBITDA	11,764	17,227	-31.7%
流動比率	1.38	1.37	
負債權益比率	0.30	0.41	

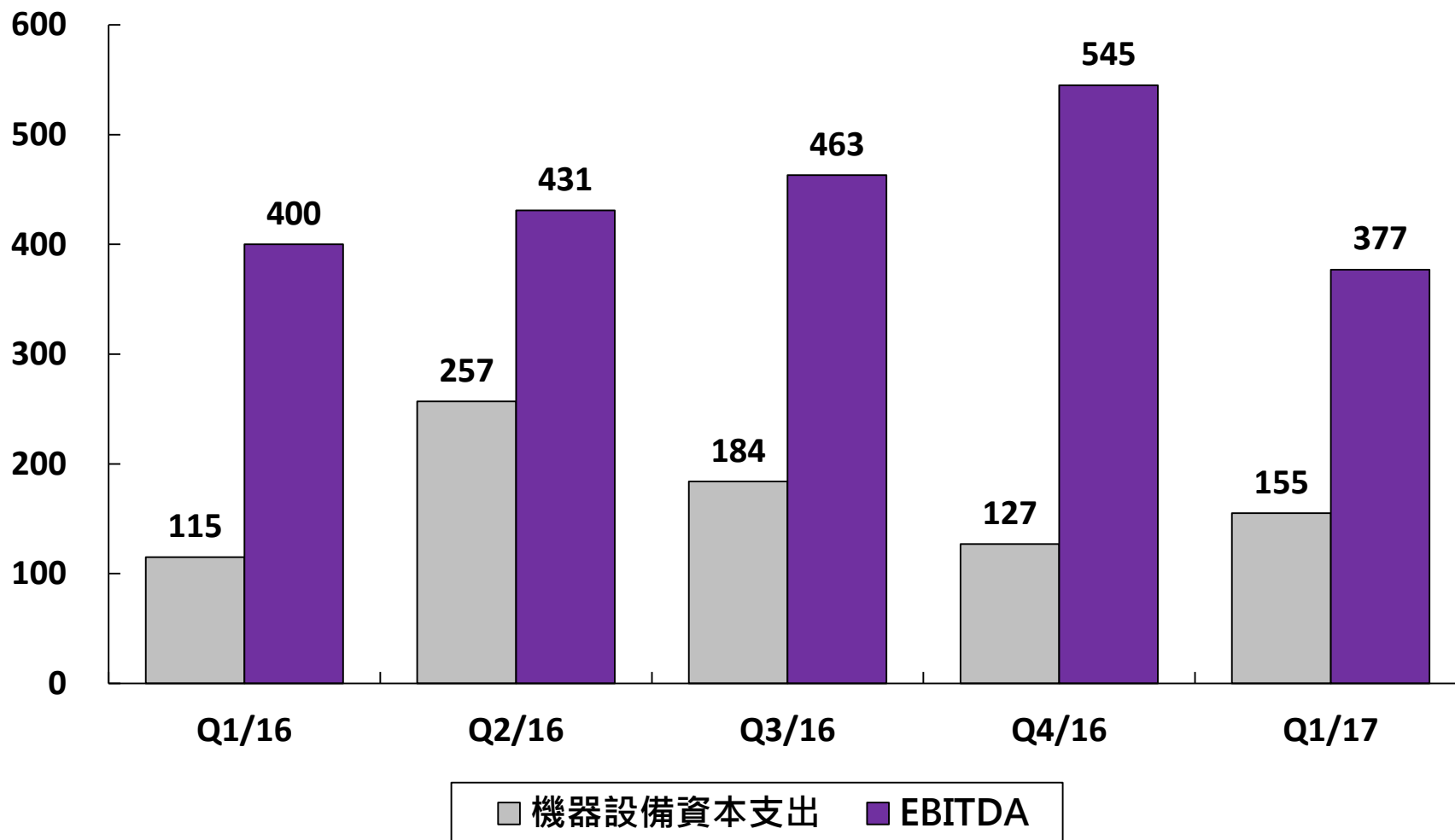


機器設備資本支出及EBITDA

(未經會計師查核)



美金百萬元



2017年第二季業績展望



根據對當前業務狀況的評估及匯率的假設，日月光公司2017年第二季的業績展望如下：

- 半導體封測事業第二季生意量與毛利率皆將與前季相當；
- 電子代工服務第二季生意量將與去年第二季與第三季平均相當；
- 電子代工服務毛利率將與前季相當。



Thank You

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